

67,200-1020
2002-0572

Abstract of the Disclosure

[0042] A method for enhancing uniformity in the polishing profile of a substrate during chemical mechanical polishing. According to a first embodiment, the method is adapted for a rotary-type chemical mechanical polisher and includes dispensing the polishing slurry onto the rotating polishing pad of the CMP apparatus in a polishing area on the polishing pad that contacts the entire surface area of the substrate. This facilitates substantially equal polishing rates and a substantially uniform polishing profile from the center to the edge regions on the surface of the substrate. According to a second embodiment, the method of the present invention is adapted for a linear-type chemical mechanical polisher and includes increasing the number of nozzles that dispense the slurry onto the polishing pad across the diameter or width of the substrate.